

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Original) A polyamide resin composition which comprises 30 to 80% by weightmass of a polyamide resin (A) comprising (i) a dicarboxylic acid component unit (a-1) consisting of 30 to 100 mol% of a dicarboxylic acid component unit derived from terephthalic acid, 0 to 70 mol% of an aromatic dicarboxylic acid component unit other than the terephthalic acid, and/or 0 to 70 mol% of an aliphatic dicarboxylic acid component unit having 4 to 20 carbon atoms (provided that the total amount of these dicarboxylic acid component units is 100 mol%) and (ii) 100 mol% of a diamine component unit (a-2) consisting of a straight chain aliphatic diamine component unit having 4 to 20 carbon atoms and/or a branched chain aliphatic diamine component unit having 4 to 20 carbon atoms, as a diamine component unit; 10 to 60% by weightmass of an inorganic filler (B); and 5 to 50% by weightmass of a white pigment (C), wherein a molded product that is injection molded from the polyamide resin composition has a flexural modulus of elasticity at 130°C of 4500 MPa to 12000 MPa.

2. (Original) A polyamide resin composition which comprises 30 to 80% by weightmass of a polyamide resin (A) comprising (i) a dicarboxylic acid component unit (a-1) consisting of 30 to 100 mol% of a dicarboxylic acid component unit derived from terephthalic acid, 0 to 70 mol% of an aromatic dicarboxylic acid component unit

other than the terephthalic acid, and/or 0 to 70 mol% of an aliphatic dicarboxylic acid component unit having 4 to 20 carbon atoms (provided that the total amount of these dicarboxylic acid component units is 100 mol%) and (ii) 100 mol% of a diamine component unit (a-2) consisting of a straight chain aliphatic diamine component unit having 4 to 20 carbon atoms and/or a branched chain aliphatic diamine component unit having 4 to 20 carbon atoms, as a diamine component unit; 10 to 60% by weightmass of an inorganic filler (B); and 5 to 50% by weightmass of a white pigment (C), wherein the polyamide resin composition further comprises an ultraviolet absorber (D) having a heating weightmass reduction ratio of 50% by weightmass or less when held at 340°C for 10 minutes under a nitrogen atmosphere, or both an ultraviolet absorber (D) and a hindered amine compound (E).

3. (Original) The polyamide resin composition according to claim 2, wherein the ultraviolet absorber (D) is one or more compounds selected from a benzotriazole compound, a triazine compound or a benzophenone compound.

4. (Currently Amended) The polyamide resin composition according to claims 1 to 3 claim 1, wherein the polyamide resin (A) has an intrinsic viscosity [η] of 0.5 to 0.9 dl/g and a melting point of 260 to 350°C.

5. (Currently Amended) The polyamide resin composition according to claims 1 to 3 claim 1, wherein the diamine component unit (a-2) of the polyamide resin (A) comprises one or more kinds selected from 1,6-diaminohexane, 1,10-diaminodecane, 1,11-diaminoundecane and 1,12-diaminododecane.

6. (Currently Amended) The polyamide resin composition according to ~~claims 1 to 3~~ claim 1, wherein the inorganic filler (B) is glass fiber.

7. (Currently Amended) The polyamide resin composition according to ~~claims 1 to 3~~ claim 1, wherein the white pigment (C) is titanium oxide.

8. (Currently Amended) A reflector plate which is formed from the polyamide resin composition according to ~~claims 1 to 3~~ claim 1.

9. (Currently Amended) A reflector plate for a light emitting diode device, which is formed from the polyamide resin composition according to ~~claims 1 to 3~~ claim 1.

10. (Original) The reflector plate for a light emitting diode according to claim 9, wherein reflectance retention is 80% or more.